CLAIMS:

- 1. An electrical device, having
- an electronic circuit, disposed at least in part on a printed circuit board (3), the circuit having power components (4) each with an arrangement for heat dissipation, and having
 - a housing frame (1) for the electronic circuit, characterized in that
- the housing frame (1) has a number of ribs (6, 7) that are joined to the respective housing frame wall but are offset, and on which the heat-carrying housing parts of the power components (4) are kept in thermal contact; and that
- the housing frame (1) can be joined by thermal contact to a heat-dissipating housing bottom (2).
- 2. The electrical device of claim 1, characterized in that
- the printed circuit board (3) of the electronic circuit is located on the side of the housing frame (1) opposite the housing bottom (2) of the electromechanical arrangement.
- The electrical device of claim 1 or 2, characterized in that
- the ribs (6) each protrude by a predetermined amount in to the housing crosswise to the respective housing frame wall.
- The electrical device of one of claims 1-3, characterized in that
 - the ribs (7) each extend parallel to the respective

housing frame wall at a predetermined spacing.

- 5. The electrical device of one of claims 1-4, characterized in that
- the housing frame (1) can be screwed firmly to the housing bottom (2).
- 6. The electrical device of one of claims 1-5, characterized in that
- the power components (4) are pressed against the ribs (6, 7) by means of metal clamps (8).
- 7. The electrical device of one of claims 1-6, characterized in that
- the housing bottom (2) is a component of an electromechanical arrangement and additionally has fins (9) for heat dissipation.